MDSA Series

SMD Low Profile High Current Molded Inductor
Size 5030



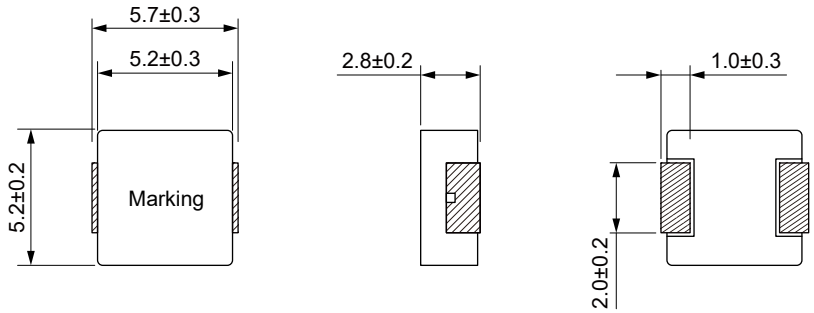
FEATURES

- Shielded construc on
-
-
-
- Ultra low buzz noise, due to composite construc on.
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- AEC-Q200 qualified
- Opera ng temperature: -55 to +155 °C(including self-temperature rise)
- Quan ty: 2000PCS

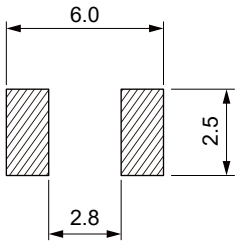
APPLICATION

- Noise filter for various drive circuitry requiring high temp. opera on and peak current handing capability.
- Boost-Converter
- Buck-Converter DC/DC

Dimensions: [mm]



Land Pattern: [mm]

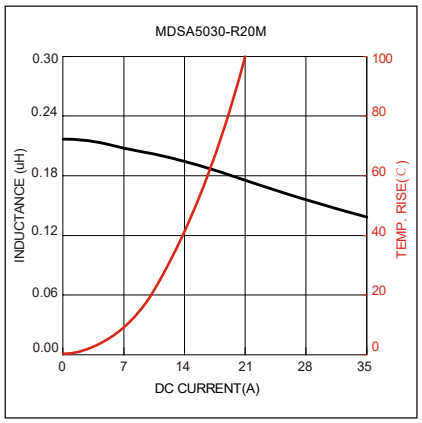


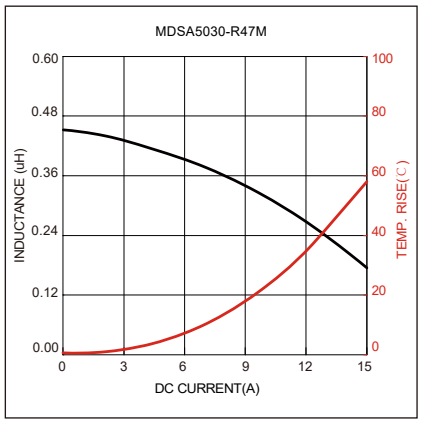
Electrical Properties:

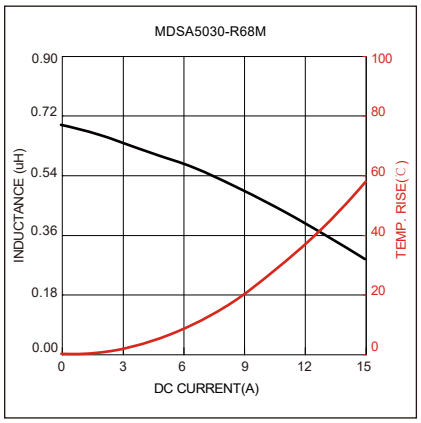
KOHER Electronic
4546 BATES DRIVE, YORBLINDA CA 92886 USA
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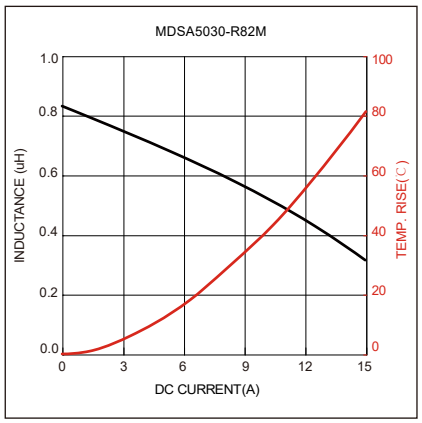
Saturation Current will cause L to drop approximately 30%
Temperature Rise Current: The actual value of DC current when the temperature rise is △T=40°C

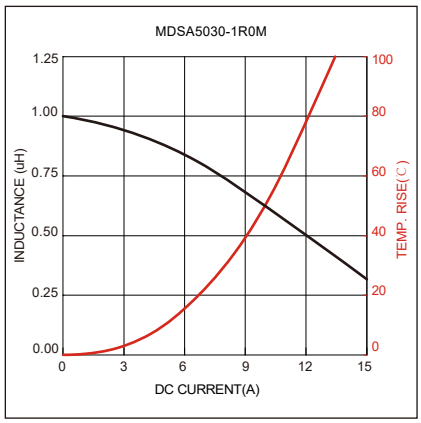
Typical Electrical Characteristics:

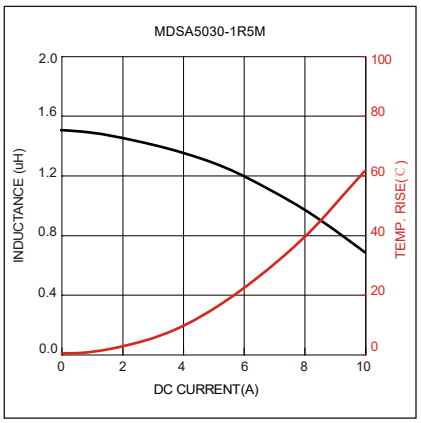


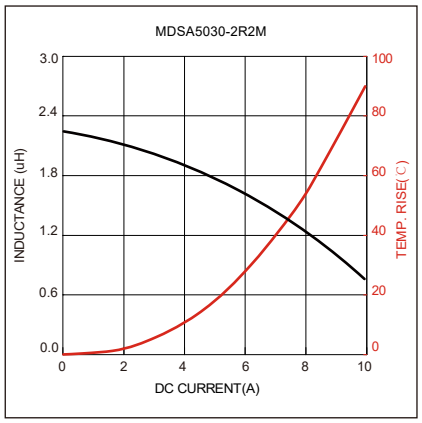


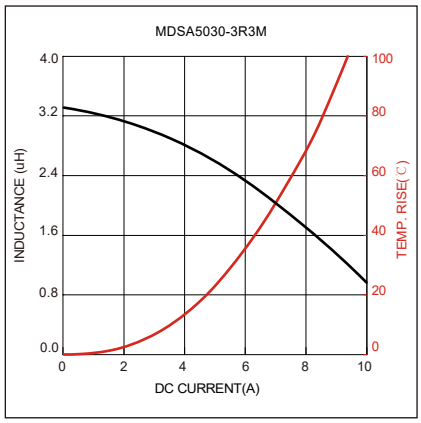


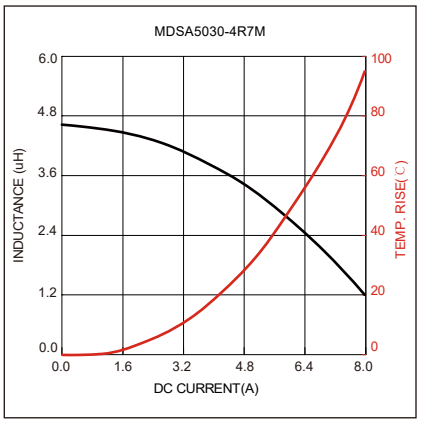


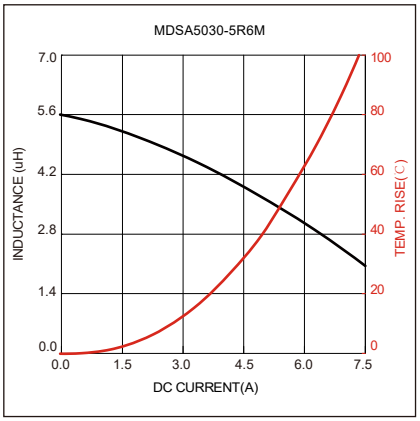


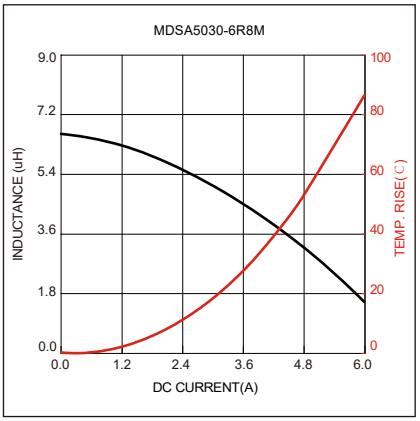


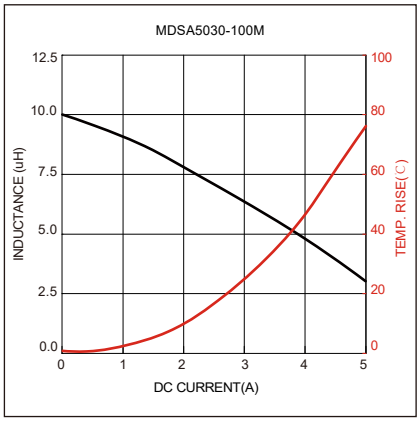


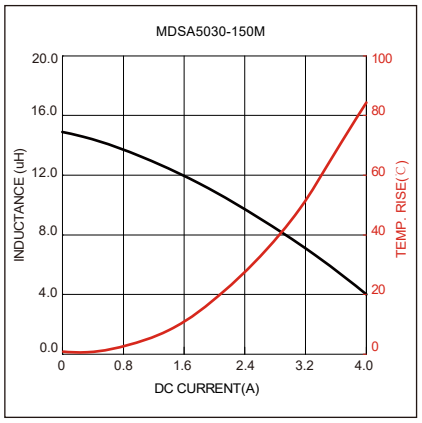




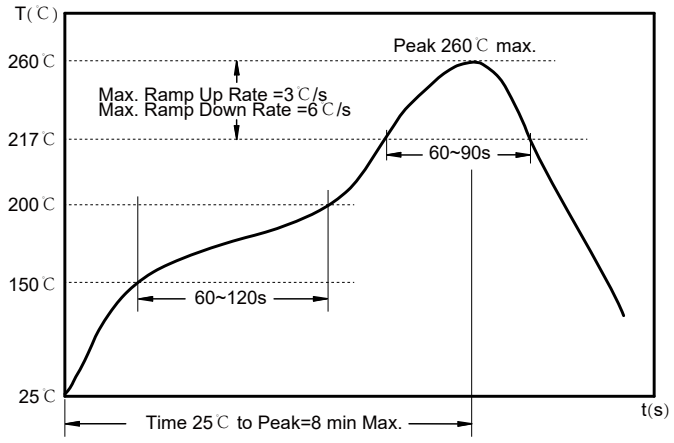

MDSA5030-5R6M
INDUCTANCE (uH)
TEMP. RISE(℃)
DC CURRENT(A)
7.0
5.6
4.2
2.8
1.4
0.0
100
80
60
40
20
0
0.0
1.5
3.0
4.5
6.0
7.5


MDSA5030-6R8M
INDUCTANCE (uH)
TEMP. RISE(℃)
DC CURRENT(A)
9.0
7.2
5.4
3.6
1.8
0.0
100
80
60
40
20
0
0.0
1.2
2.4
3.6
4.8
6.0


MDSA5030-100M
INDUCTANCE (uH)
TEMP. RISE(℃)
DC CURRENT(A)
12.5
10.0
7.5
5.0
2.5
0.0
100
80
60
40
20
0
0
1
2
3
4
5


MDSA5030-150M
INDUCTANCE (uH)
TEMP. RISE(℃)
DC CURRENT(A)
20.0
16.0
12.0
8.0
4.0
0.0
100
80
60
40
20
0
0
0.8
1.6
2.4
3.2
4.0

Soldering Reflow:



Preheat condition: 150 ~200℃/ 60~120 sec.

Allowed time above 217℃: 60~90 sec.

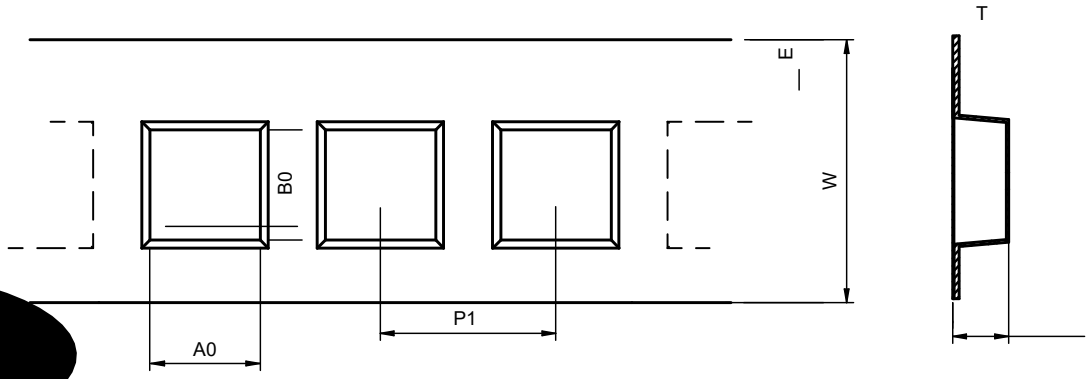
Max temperature: 260℃.

Max time at max temperature: 10 sec.

Allowed Reflow time: 2x max.

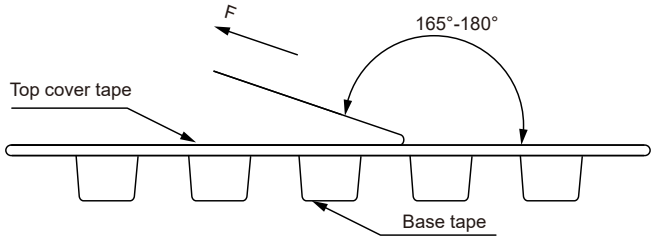
Packaging Information:

Tape Dimension:



Series	A0 (mm)	B0 (mm)	D (mm)	P0 (mm)	P1 (mm)	W (mm)	K0 (mm)	E (mm)	T (mm)
MDSA5030	5.5±0.1	5.9±0.1	1.5±0.1	4.0±0.1	8.0±0.1	12.0±0.3	3.3±0.1	1.75±0.1	0.35±0.05

Peel force of top cover tape:



The peel force of top cover tape shall be between 0.1 to 1.3 N

Product Marking:

Marking	K+Printing (Inductance)

Reel Dimension：[mm]



Packaging Quantity: